Abstract of the Disclosure

A semiconductor wafer assembly is constituted such that the back surface of a tape is stuck to the surface of a frame and a semiconductor wafer is stuck to the surface of the tape. A machining apparatus has chuck tables for supporting the semiconductor wafer assembly, and each of the chuck tables has a semiconductor wafer placing surface for supporting the back surface of the tape to which the semiconductor wafer is stuck and an annular frame placing surface for supporting the back surface of the frame, formed, in the outer peripheral side of the semiconductor wafer mounting surface, at a position below the semiconductor wafer placing surface with a level difference therebetween.

This Sheet Has Been Replaced

